

ABSTRACT

PHOTOSENSITIVE RESIN COMPOSITION AND LAMINATE

A photosensitive resin composition which has satisfactory compatibility in dry-film formation, has sensitivity equally to two lights of i-line and h-line, is excellent in resolution and adhesion, and can be developed with an alkaline aqueous solution. Also provided are: a layered photosensitive-resin product including the photosensitive resin composition; a method of forming a resist pattern on a substrate with the layered photosensitive-resin product; and a use of the resist pattern. The photosensitive resin composition comprises: (a) 20-90 mass% thermoplastic copolymer which includes comonomer units derived from an  $\alpha,\beta$ -unsaturated monomer having a carboxy group and which has an acid equivalent of 100-600 and a weight-average molecular weight of 5,000-500,000; (b) 5-75 mass% addition-polymerizable monomer having at least one ethylenically unsaturated terminal group; (c) 0.01-30 mass% photopolymerization initiator comprising a triarylimidazolyl dimer; and (d) 0.001-10 mass% pyrazoline compound represented by a specific general formula.